#### T-1 (3mm) BI-LEVEL LED INDICATOR

Part Number: L-130WCP/2EYW

High Efficiency Red Yellow

#### **Features**

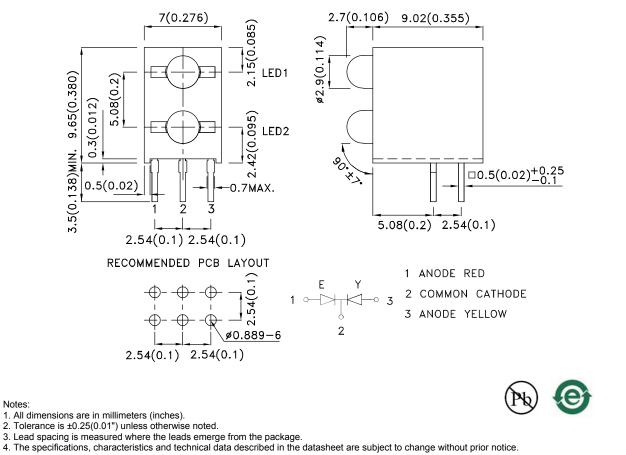
- Bi-level right angle housing LED.
- Pre-trimmed leads for pc board mounting.
- Black case enhances contrast ratio.
- High reliability.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- · RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

#### **Package Dimensions**



Notes:

REV NO: V.10A **CHECKED: Allen Liu**  DATE: SEP/25/2013 DRAWN: Y.Liu

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#### Solaction Guida

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-130WCP/2EYW	High Efficiency Red (GaAsP/GaP)	- White Diffused	12	30	60°
			*10	*24	
	Yellow (GaAsP/GaP)		10	20	
			*10	*20	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
\*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Yellow	627 590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Yellow	617 588		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Yellow	45 35		nm	I⊧=20mA
С	Capacitance	High Efficiency Red Yellow	15 20		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	High Efficiency Red Yellow	2 2.1	2.5 2.5	V	I⊧=20mA
lr	Reverse Current	High Efficiency Red Yellow		10 10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

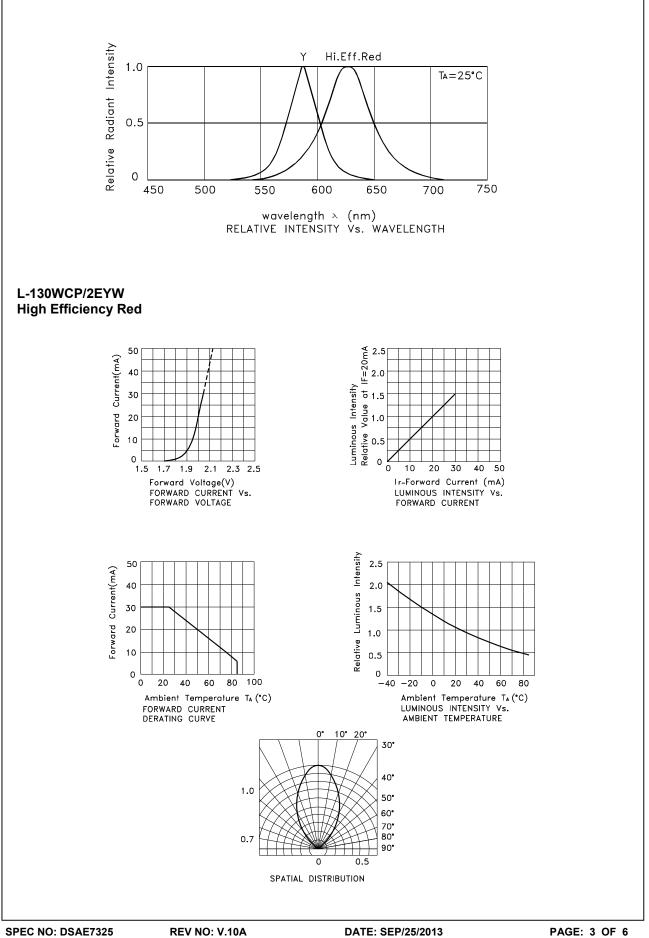
Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

#### Absolute Maximum Ratings at TA=25°C

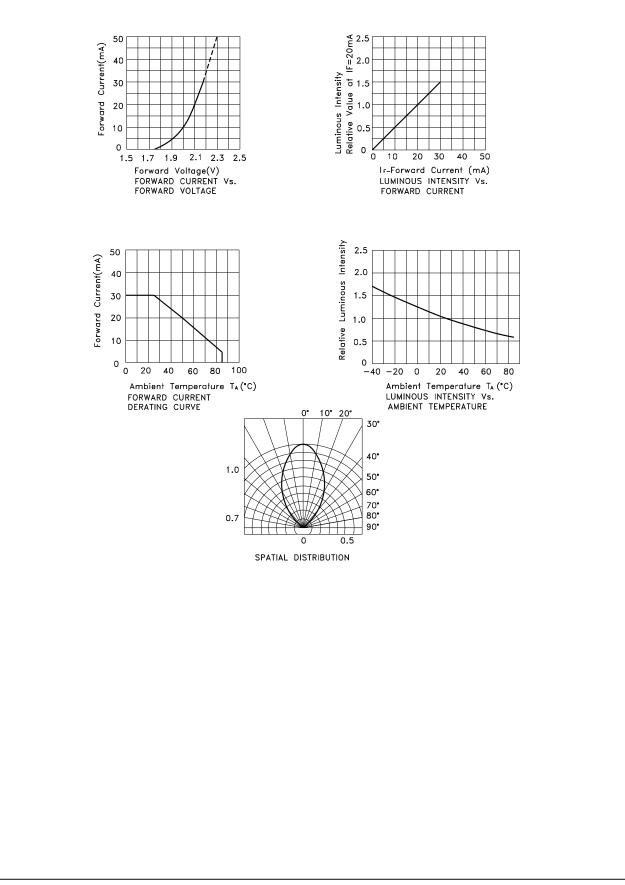
Parameter	High Efficiency Red	Yellow	Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage		V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				
Notes <sup>.</sup>					

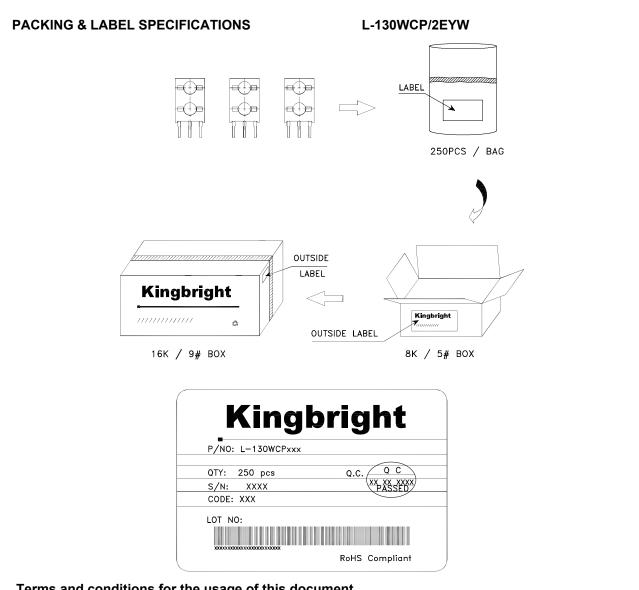
Notes

1.1/10 Duty Cycle, 0.1ms Pulse Width.
 2.2mm below package base.
 3.5mm below package base.



Yellow



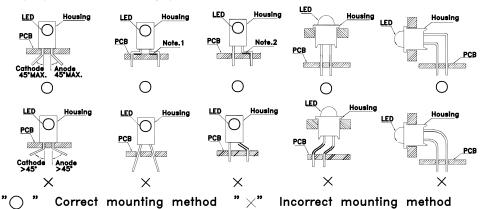


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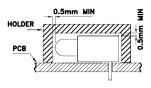
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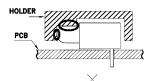
#### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.





- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through-hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:

